BIPOLAR ANALOG INTEGRATED CIRCUIT $\mu PC8232T5N$

SiGe:C LOW NOISE AMPLIFIER FOR GPS

DESCRIPTION

The μ PC8232T5N is a silicon germanium carbon (SiGe:C) monolithic integrated circuit designed as low noise amplifier for GPS. This device exhibits low noise figure and high power gain characteristics, so this IC can improve the sensitivity of GPS receiver. In addition, the μ PC8232T5N which is included output matching circuit contributes to reduce external components and system size.

The package is a 6-pin plastic TSON (<u>Thin Small Out-line Non-leaded</u>) suitable for surface mount.

This IC is manufactured using our UHS4 (Ultra High Speed Process) SiGe:C bipolar process.

FEATURES

- Low noise
- : NF = 0.95 dB TYP. @ fin = 1 575 MHz : GP = 17 dB TYP. @ fin = 1 575 MHz
- High gainLow current consumption
- : Icc = 3.0 mA TYP. @ Vcc = 3.0 V
- Built-in power-saving function
- High-density surface mounting $\,$: 6-pin plastic TSON package (1.5 \times 1.5 \times 0.37 mm)
- Included output matching circuit
- Included very robust bandgap regulator (Small Vcc and T_A dependence)
- Included protection circuits for ESD

APPLICATION

Low noise amplifier for GPS

ORDERING INFORMATION

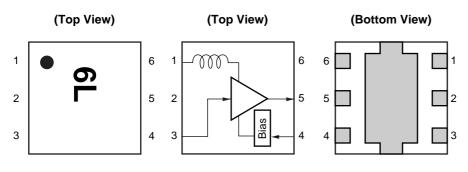
Part Number	Order Number	Package	Marking	Supplying Form
µРС8232Т5N-Е2	μΡC8232T5N-E2-A	6-pin plastic TSON (Pb-Free)	6L	8 mm wide embossed tapingPin 1, 6 face the perforation side of the tapeQty 3 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office. Part number for sample order: *µ*PC8232T5N-A

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name		
1	Vcc		
2	GND		
3	INPUT		
4	Power Save		
5	OUTPUT		
6	Vcc		

Remark Exposed pad : GND

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Test Conditions	Ratings	Unit
Supply Voltage	Vcc	TA = +25°C	4.0	V
Power-Saving Voltage	Vps	TA = +25°C	4.0	V
Total Power Dissipation	Ptot		150	mW
Operating Ambient Temperature	TA		-40 to +85	°C
Storage Temperature	Tstg		–55 to +150	°C
Input Power	Pin		+10	dBm

RECOMMENDED OPERATING RANGE

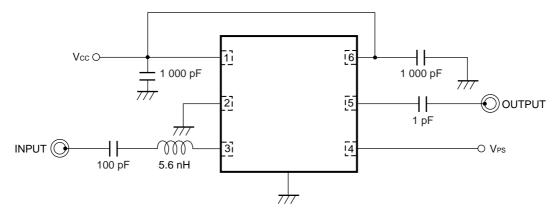
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	Vcc	2.5	3.0	3.3	V
Operating Ambient Temperature	TA	-40	+25	+85	°C
Power Save Turn-on Voltage	VPSon	1.6	-	Vcc	V
Power Save Turn-off Voltage	VPSoff	0	-	0.4	V

ELECTRICAL CHARACTERISTICS

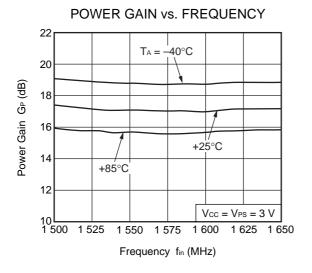
(TA = +25°C, Vcc = VPs = 3.0 V, fin = 1 575 MHz, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	Icc	No Signal (VPs = 3.0 V)	2.3	3.0	4.1	mA
		At Power-Saving Mode (VPs = 0 V)	-	-	1	μA
Power Gain	G₽	Pin = -35 dBm	15	17	19	dB
Noise Figure	NF		-	0.95	1.25	dB
Input 3rd Order Distortion Intercept Point	IIP3	fin1 = 1 574 MHz, fin2 = 1 575 MHz	-	-8	-	dBm
Input Return Loss	RLin		7	10	-	dB
Output Return Loss	RLout		10	20	-	dB
Isolation	ISL		-	40	-	dB
Gain 1 dB Compression Input Power	Pin (1 dB)		-	-21	-	dBm

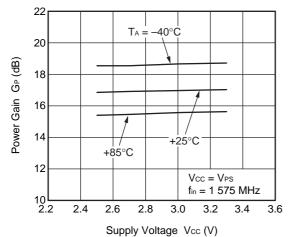
TEST CIRCUIT



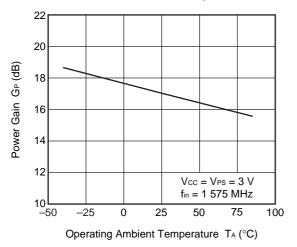
TYPICAL CHARACTERISTICS (T_A = +25°C, unless otherwise specified)



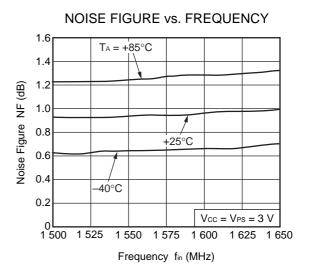
POWER GAIN vs. SUPPLY VOLTAGE



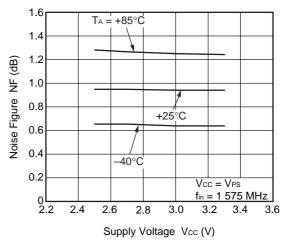




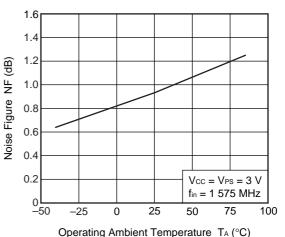


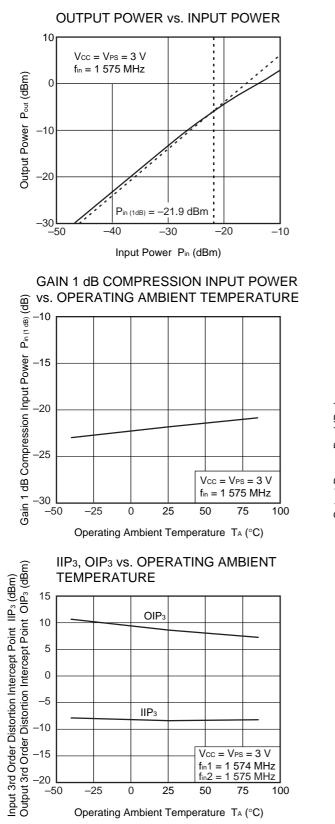


NOISE FIGURE vs. SUPPLY VOLTAGE



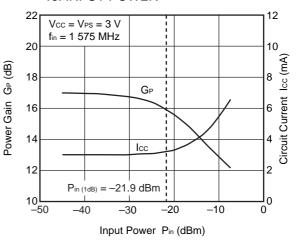
NOISE FIGURE vs. OPERATING AMBIENT TEMPERATURE



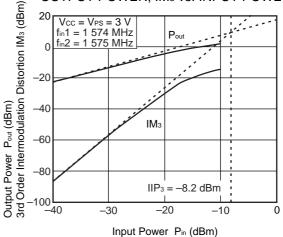


Remark The graphs indicate nominal characteristics.

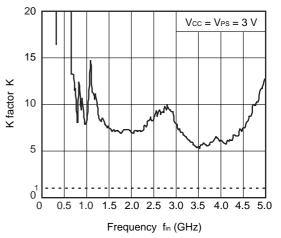
POWER GAIN, CIRCUIT CURRENT vs. INPUT POWER

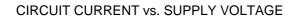


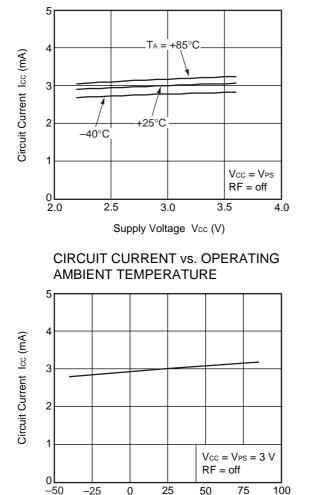
OUTPUT POWER, IM3 vs. INPUT POWER







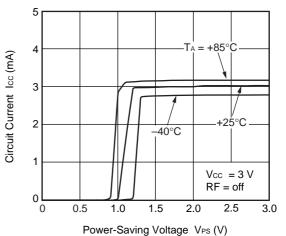


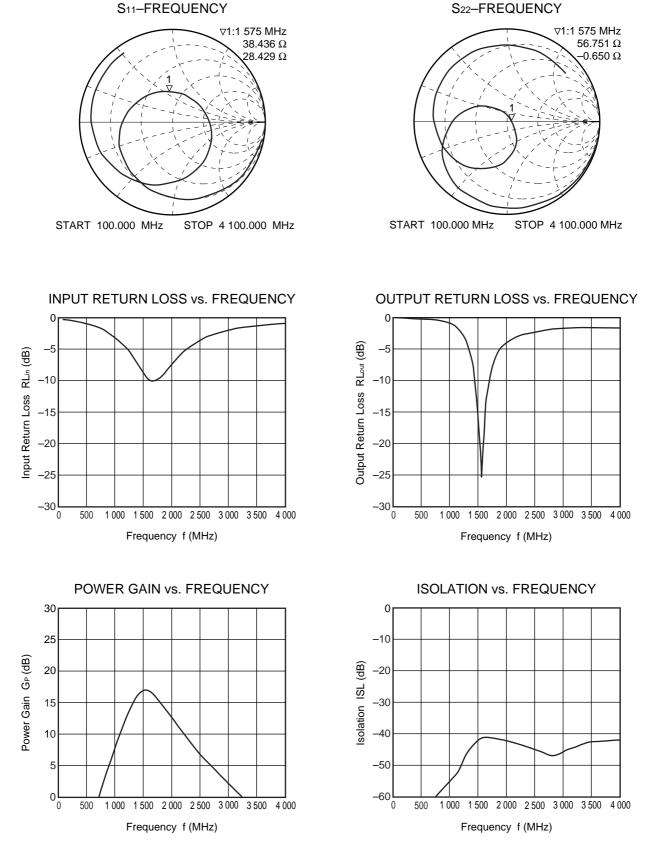


Operating Ambient Temperature T_A (°C)

Remark The graphs indicate nominal characteristics.

CIRCUIT CURRENT vs. POWER-SAVING VOLTAGE





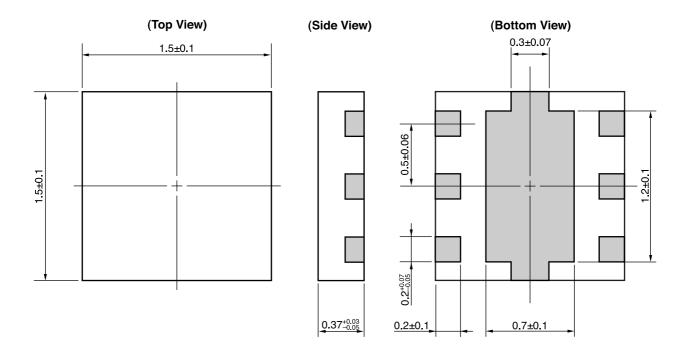
S-PARAMETERS (T_A = +25°C, V_Cc = V_Ps = 3.0 V, monitored at connector on board)

Remark The graphs indicate nominal characteristics.

Data Sheet PU10672EJ01V0DS

PACKAGE DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)



NOTES ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation). All the ground terminals must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to Vcc line.
- (4) Do not supply DC voltage to INPUT pin.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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- "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

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CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM	Not De	etected	
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not Detected		
РВВ	< 1000 PPM	Not Detected		
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

In no event shall CEL's liability arising out of such information exceed the total purchase price of the CEL part(s) at issue sold by CEL to customer on an annual basis.

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